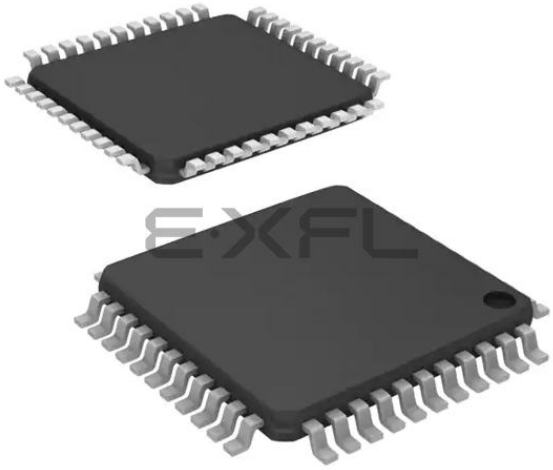

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1904-i-pt

3.2.1.1 STATUS Register

The STATUS register, shown in Register 3-1, contains:

- the arithmetic status of the ALU
- the Reset status

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as '`000u u1uu`' (where u = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits (Refer to **Section 21.0 "Instruction Set Summary"**).

Note:	The C and DC bits operate as $\overline{\text{Borrow}}$ and $\overline{\text{Digit Borrow}}$ out bits, respectively, in subtraction.

REGISTER 3-1: STATUS: STATUS REGISTER

U-0	U-0	U-0	R-1/q	R-1/q	R/W-0/u	R/W-0/u	R/W-0/u
—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC(1)	C(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **$\overline{TO}$:** Time-out bit
- 1 = After power-up, `CLRWDT` instruction or `SLEEP` instruction
- 0 = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-Down bit
- 1 = After power-up or by the `CLRWDT` instruction
- 0 = By execution of the `SLEEP` instruction

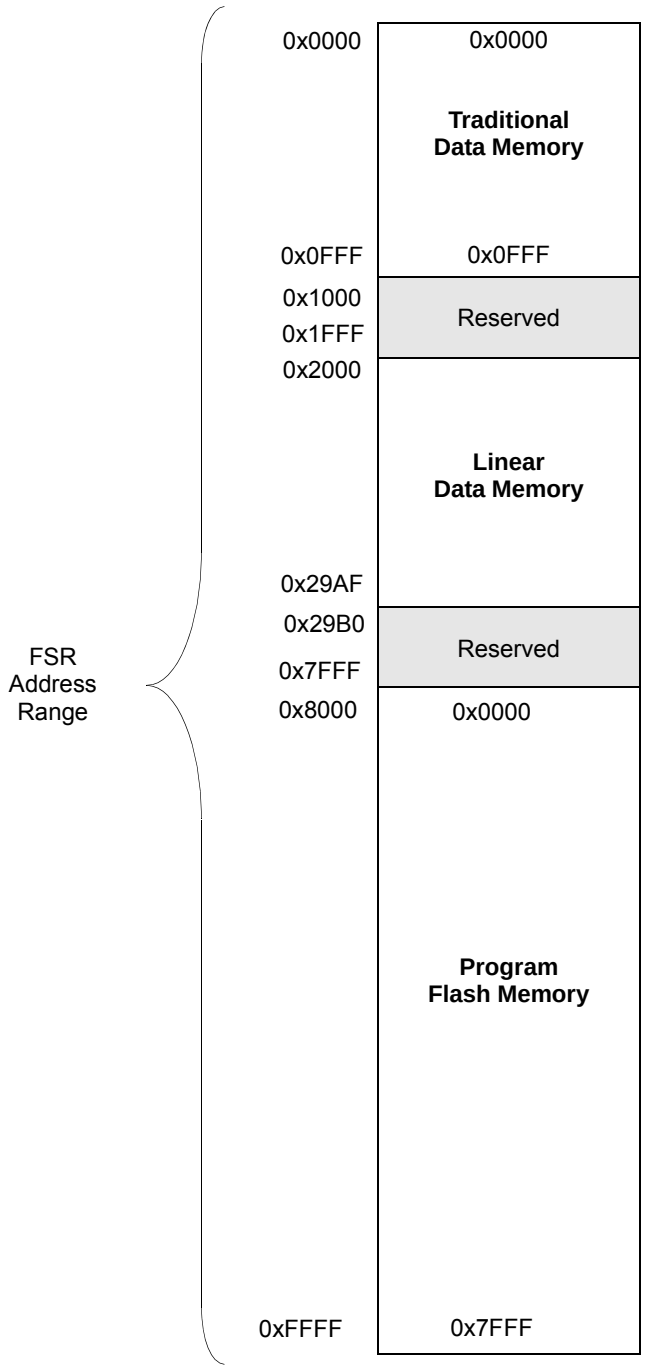
bit 2 **Z:** Zero bit
- 1 = The result of an arithmetic or logic operation is zero
- 0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{\text{Digit Borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(1)
- 1 = A carry-out from the 4th low-order bit of the result occurred
- 0 = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{\text{Borrow}}$ bit(1) (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(1)
- 1 = A carry-out from the Most Significant bit of the result occurred
- 0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{\text{Borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

FIGURE 3-9: INDIRECT ADDRESSING



Note: Not all memory regions are completely implemented. Consult device memory tables for memory limits.

6.4 Oscillator Control Registers

REGISTER 6-1: OSCCON: OSCILLATOR CONTROL REGISTER

U-0	R/W-0/0	R/W-1/1	R/W-1/1	R/W-1/1	U-0	R/W-0/0	R/W-0/0
—	IRCF<3:0>				—	SCS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **Unimplemented:** Read as ‘0’

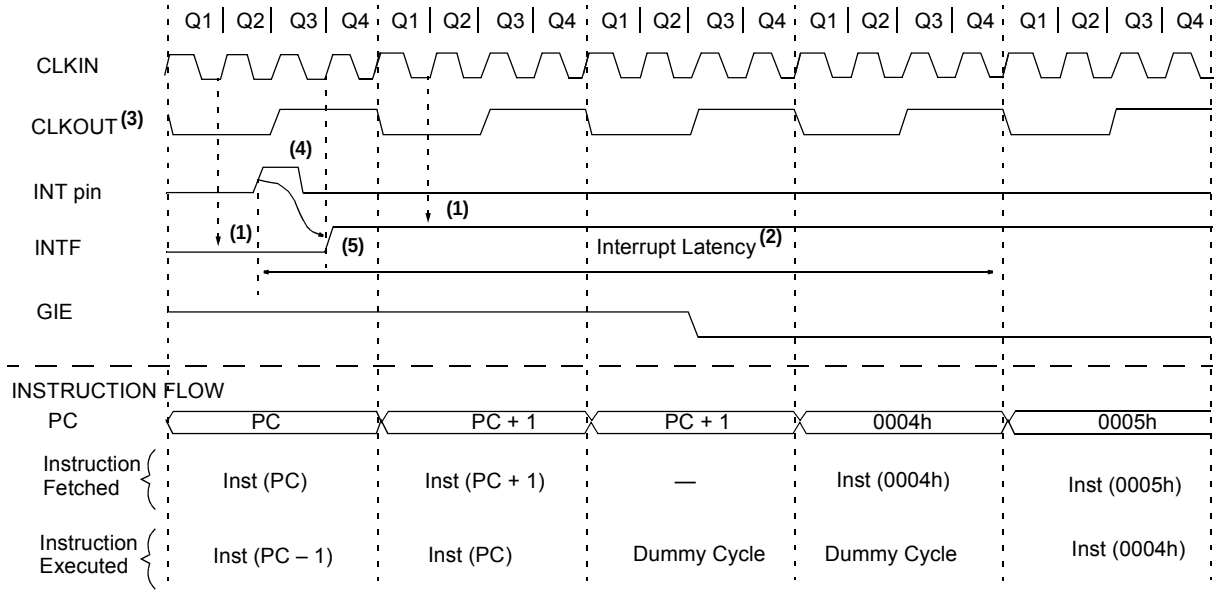
bit 6-3 **IRCF<3:0>:** Internal Oscillator Frequency Select bits
000x = 31 kHz LF
001x = 31.25 kHz
0100 = 62.5 kHz
0101 = 125 kHz
0110 = 250 kHz
0111 = 500 kHz (default upon Reset)
1000 = 125 kHz(1)
1001 = 250 kHz(1)
1010 = 500 kHz(1)
1011 = 1 MHz
1100 = 2 MHz
1101 = 4 MHz
1110 = 8 MHz
1111 = 16 MHz

bit 2 **Unimplemented:** Read as ‘0’

bit 1-0 **SCS<1:0>:** System Clock Select bits
1x = Internal oscillator block
01 = Secondary oscillator
00 = Clock determined by FOSC<1:0> in Configuration Word 1.

Note 1: Duplicate frequency derived from HFINTOSC.

FIGURE 7-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT not available in all Oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 22.0 "Electrical Specifications"**".

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

9.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator. Time intervals in this chapter are based on a nominal interval of 1ms. See **Section 22.0 "Electrical Specifications"** for the LFINTOSC tolerances.

9.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Word 1. See Table 9-1.

9.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Word 1 are set to '11', the WDT is always on.

WDT protection is active during Sleep.

9.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Word 1 are set to '10', the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

9.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Word 1 are set to '01', the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 9-1 for more details.

TABLE 9-1: WDT OPERATING MODES

WDTE<1:0>	SWDTEN	Device Mode	WDT Mode
11	X	X	Active
10	X	Awake	Active
		Sleep	Disabled
01	1	X	Active
	0		Disabled
00	X	X	Disabled

9.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds (nominal). After a Reset, the default time-out period is two seconds.

9.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- CLRWDT instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail event
- WDT is disabled
- Oscillator Start-up TImer (OST) is running

See Table 9-2 for more information.

9.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting.

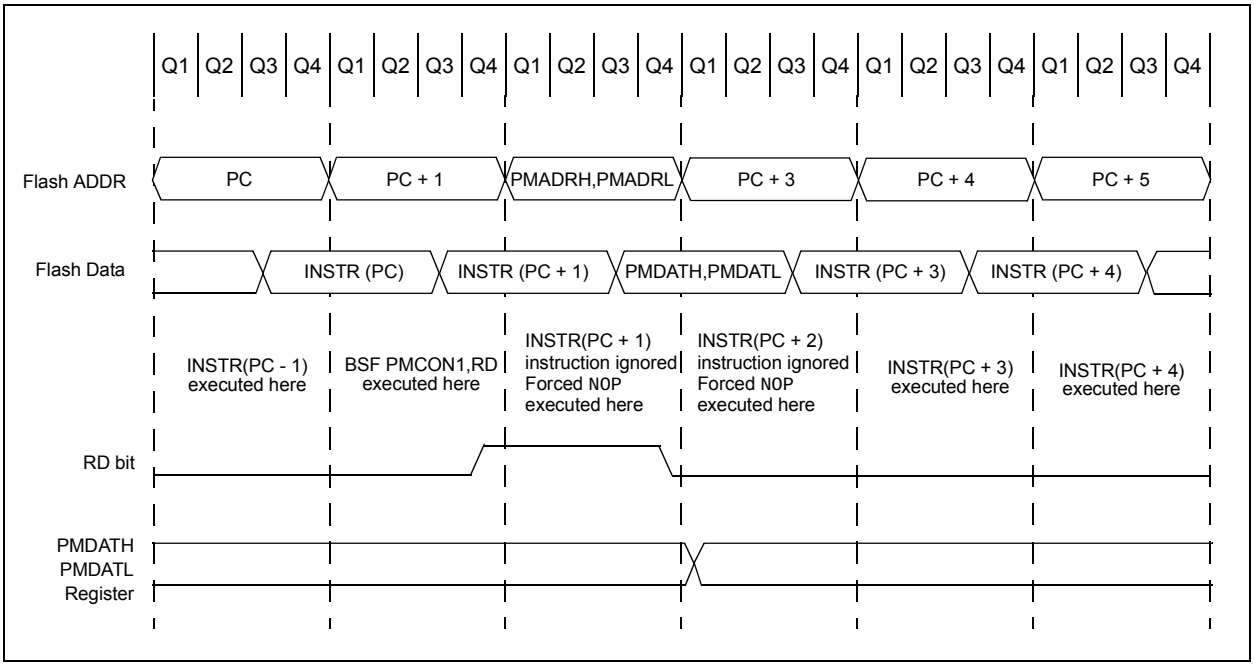
When the device exits Sleep, the WDT is cleared again. The WDT remains clear until the OST, if enabled, completes. See **Section 6.0 "Oscillator Module"** for more information on the OST.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the event. See **Section 3.0 "Memory Organization"** and STATUS register (**Register 3-1)** for more information.

TABLE 9-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = 00	Cleared
WDTE<1:0> = 01 and SWDTEN = 0	
WDTE<1:0> = 10 and enter Sleep	
CLRWDT Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = T1OSC, EXTRC, INTOSC, EXTCLK	
Change INTOSC divider (IRCF bits)	Unaffected

FIGURE 10-2: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



EXAMPLE 10-1: FLASH PROGRAM MEMORY READ

```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI : PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; Select Bank for PMCON registers
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    MOVLW    PROG_ADDR_HI     ;
    MOVWL    PMADRH           ; Store MSB of address

    BCF      PMCON1,CFGS      ; Do not select Configuration Space
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Ignored (Figure 10-1)
    NOP                       ; Ignored (Figure 10-1)

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

10.2.2 FLASH MEMORY UNLOCK SEQUENCE

The unlock sequence is a mechanism that protects the Flash Program Memory from unintended self-write programming or erasing. The sequence must be executed and completed without interruption to successfully complete any of the following operations:

- Row Erase
- Load program memory write latches
- Write of program memory write latches to program memory
- Write of program memory write latches to User IDs

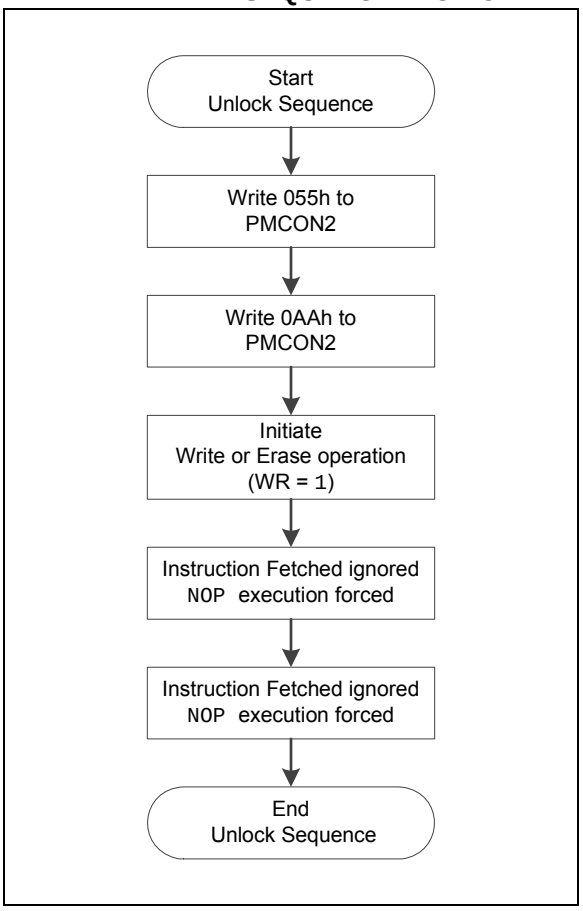
The unlock sequence consists of the following steps:

1. Write 55h to PMCON2
2. Write AAh to PMCON2
3. Set the WR bit in PMCON1
4. NOP instruction
5. NOP instruction

Once the WR bit is set, the processor will always force two NOP instructions. When an Erase Row or Program Row operation is being performed, the processor will stall internal operations (typical 2 ms), until the operation is complete and then resume with the next instruction. When the operation is loading the program memory write latches, the processor will always force the two NOP instructions and continue uninterrupted with the next instruction.

Since the unlock sequence must not be interrupted, global interrupts should be disabled prior to the unlock sequence and re-enabled after the unlock sequence is completed.

FIGURE 10-3: FLASH PROGRAM MEMORY UNLOCK SEQUENCE FLOWCHART



11.3 PORTC Registers

PORTC is an 8-bit wide bidirectional port. The corresponding data direction register is TRISC (Register 11-6). Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 11-1 shows how to initialize an I/O port.

Reading the PORTC register (Register 11-5) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATC).

The TRISC register (Register 11-6) controls the PORTC pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISC register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

11.3.1 PORTC FUNCTIONS AND OUTPUT PRIORITIES

Each PORTC pin is multiplexed with other functions. The pins, their combined functions and their output priorities are shown in Table 11-7.

When multiple outputs are enabled, the actual pin control goes to the peripheral with the highest priority.

Analog input and some digital input functions are not included in the list below. These input functions can remain active when the pin is configured as an output. Certain digital input functions override other port functions and are included in Table 11-7.

TABLE 11-7: PORTC OUTPUT PRIORITY

Pin Name	Function Priority(1)
RC0	T1OSO T1CKI RC0
RC1	T1OSI RC1
RC2	SEG2 RC2
RC3	SEG6 RC3
RC4	SEG11 T1G RC4
RC5	SEG10 RC5
RC6	SEG9 RC6 TX/CK
RC7	SEG8 RC7 RX/DT

Note 1: Priority listed from highest to lowest.

TABLE 18-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 16.000 MHz			FOSC = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	13332	300.0	0.00	9215
1200	1200	-0.01	4166	1200	0.00	3839	1200.1	0.01	3332	1200	0.00	2303
2400	2400	0.02	2082	2400	0.00	1919	2399.5	-0.02	1666	2400	0.00	1151
9600	9597	-0.03	520	9600	0.00	479	9592	-0.08	416	9600	0.00	287
10417	10417	0.00	479	10425	0.08	441	10417	0.00	383	10433	0.16	264
19.2k	19.23k	0.16	259	19.20k	0.00	239	19.23k	0.16	207	19.20k	0.00	143
57.6k	57.47k	-0.22	86	57.60k	0.00	79	57.97k	0.64	68	57.60k	0.00	47
115.2k	116.3k	0.94	42	115.2k	0.00	39	114.29k	-0.79	34	115.2k	0.00	23

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 8.000 MHz			FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	0.01	3332	300.0	0.00	3071	300.1	0.04	832
1200	1200	-0.02	1666	1200	0.04	832	1200	0.00	767	1202	0.16	207
2400	2401	0.04	832	2398	0.08	416	2400	0.00	383	2404	0.16	103
9600	9615	0.16	207	9615	0.16	103	9600	0.00	95	9615	0.16	25
10417	10417	0	191	10417	0.00	95	10473	0.53	87	10417	0.00	23
19.2k	19.23k	0.16	103	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	12
57.6k	57.14k	-0.79	34	58.82k	2.12	16	57.60k	0.00	15	—	—	—
115.2k	117.6k	2.12	16	111.1k	-3.55	8	115.2k	0.00	7	—	—	—

TABLE 18-9: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
BAUD2CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	153
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	65
PIE1	TMR1GIE	ADIE	RCIE(1)	TXIE(1)	—	—	—	TMR1IE	66
PIR1	TMR1GIF	ADIF	RCIF(1)	TXIF(1)	—	—	—	TMR1IF	68
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	152
SPBRGL	EUSART Baud Rate Generator, Low Byte								154*
SPBRGH	EUSART Baud Rate Generator, High Byte								154*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	98
TXREG	EUSART Transmit Register								144*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for synchronous slave transmission.

* Page provides register information.

Note 1: PIC16LF1904/7 only.

19.0 LIQUID CRYSTAL DISPLAY (LCD) DRIVER MODULE

The Liquid Crystal Display (LCD) driver module generates the timing control to drive a static or multiplexed LCD panel. In the PIC16LF1904/6/7 device, the module drives the panels of up to four commons and up to 116 total segments. The LCD module also provides control of the LCD pixel data.

The LCD driver module supports:

- Direct driving of LCD panel
- Three LCD clock sources with selectable prescaler
- Up to four common pins:
  - Static (1 common)
  - 1/2 multiplex (2 commons)
  - 1/3 multiplex (3 commons)
  - 1/4 multiplex (4 commons)
- 19 Segment pins (PIC16LF1906 only)
- 29 Segment pins (PIC16LF1904/7 only)
- Static, 1/2 or 1/3 LCD Bias

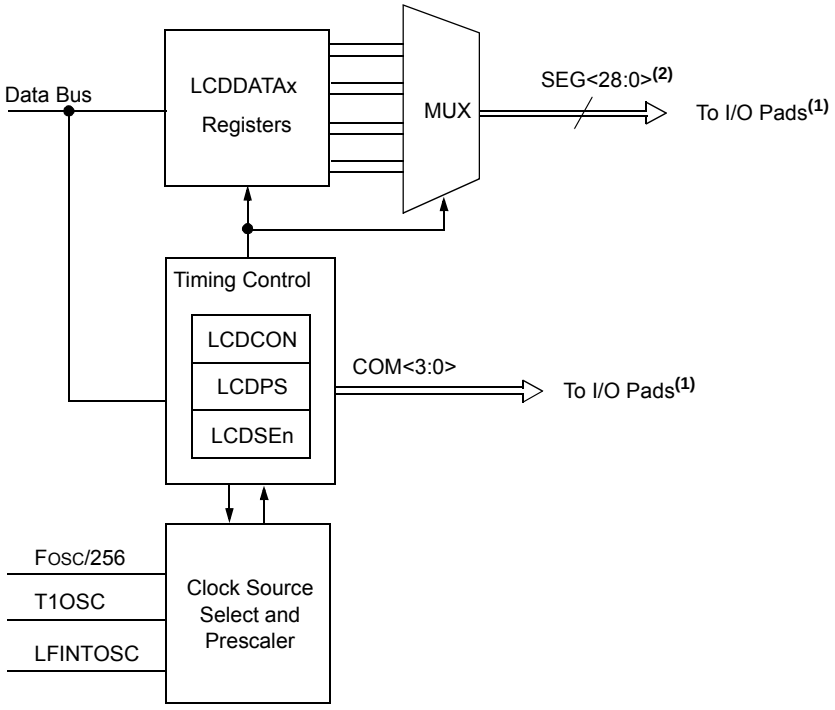
Note:	COM3 and SEG15 share the same physical pin on the PIC16LF1906, therefore SEG15 is not available when using 1/4 multiplex displays.

19.1 LCD Registers

The module contains the following registers:

- LCD Control register (LCDCON)
- LCD Phase register (LCDPS)
- LCD Reference Ladder register (LCDRL)
- LCD Contrast Control register (LCDCST)
- LCD Reference Voltage Control register (LCDREF)
- Up to 4 LCD Segment Enable registers (LCDSEn)
- Up to 16 LCD data registers (LCDDATAn)

FIGURE 19-1: LCD DRIVER MODULE BLOCK DIAGRAM



Note 1: These are not directly connected to the I/O pads, but may be tri-stated, depending on the configuration of the LCD module.

2: COM3 and SEG15 share the same physical pin, therefore SEG15 is not available when using 1/4 multiplex displays. For the PIC16LF1906 device only.

REGISTER 19-4: LCDCST: LCD CONTRAST CONTROL REGISTER

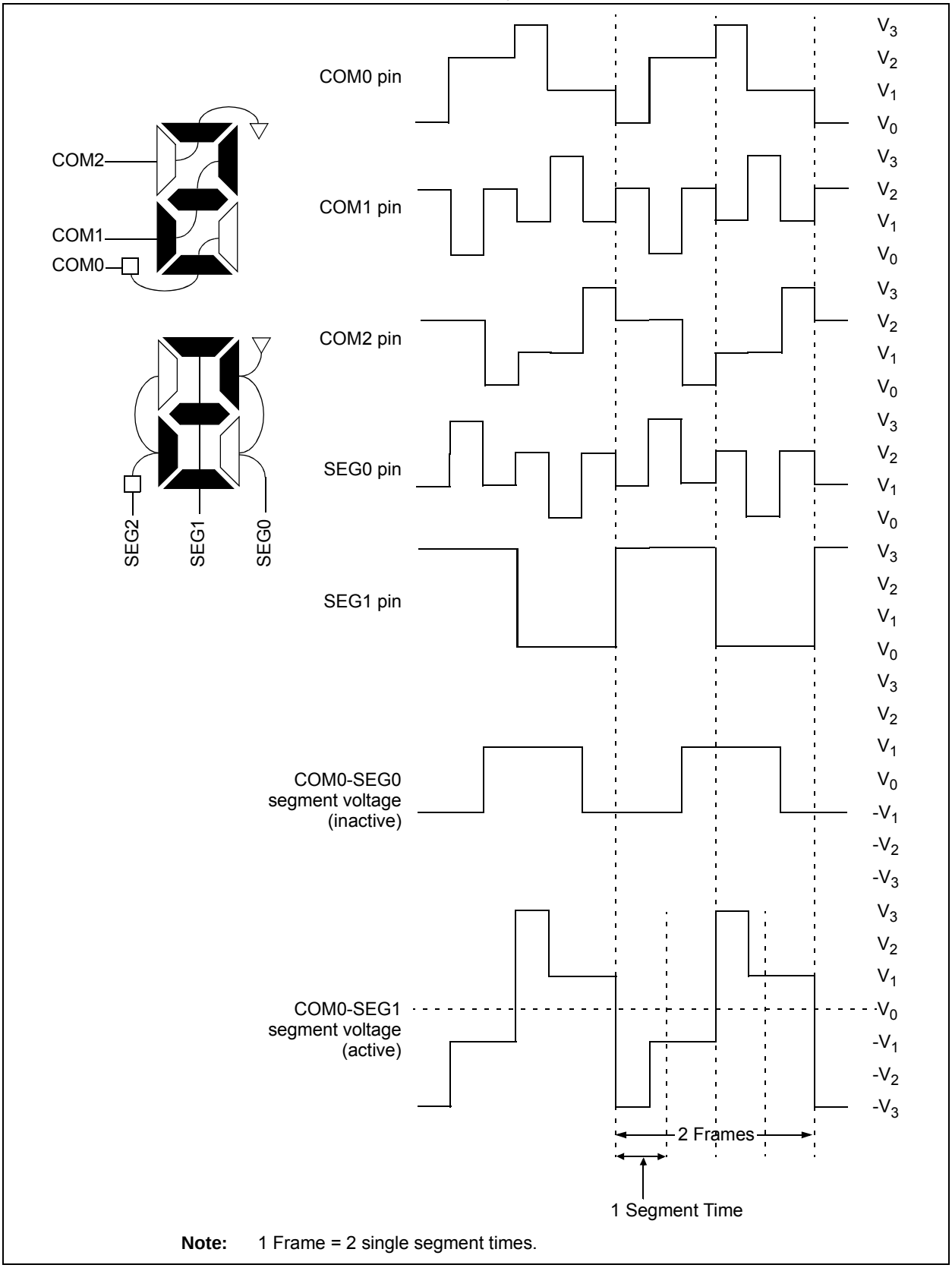
U-0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	—	—	LCDCST<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	C = Only clearable bit

bit 7-3 **Unimplemented:** Read as ‘0’

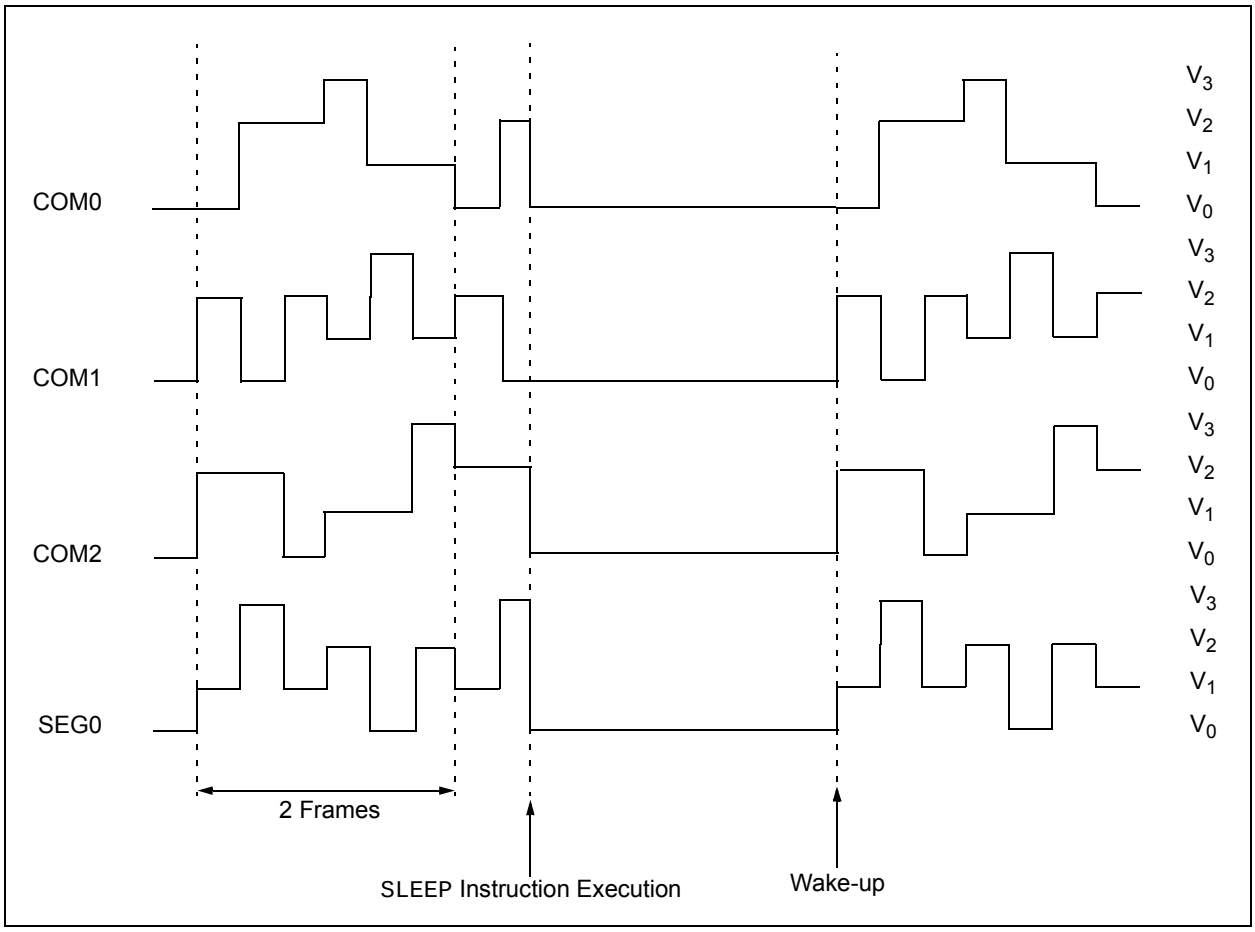
bit 2-0 **LCDCST<2:0>:** LCD Contrast Control bits
Selects the resistance of the LCD contrast control resistor ladder
Bit Value = Resistor ladder
000 = Minimum Resistance (Maximum contrast). Resistor ladder is shorted.
001 = Resistor ladder is at 1/7th of maximum resistance
010 = Resistor ladder is at 2/7th of maximum resistance
011 = Resistor ladder is at 3/7th of maximum resistance
100 = Resistor ladder is at 4/7th of maximum resistance
101 = Resistor ladder is at 5/7th of maximum resistance
110 = Resistor ladder is at 6/7th of maximum resistance
111 = Resistor ladder is at maximum resistance (Minimum contrast).

FIGURE 19-16: TYPE-B WAVEFORMS IN 1/3 MUX, 1/3 BIAS DRIVE



Note: 1 Frame = 2 single segment times.

FIGURE 19-20: SLEEP ENTRY/EXIT WHEN SLPEN = 1



19.12 Configuring the LCD Module

The following is the sequence of steps to configure the LCD module.

1. Select the frame clock prescale using bits LP<3:0> of the LCDPS register.
2. Configure the appropriate pins to function as segment drivers using the LCDSEn registers.
3. Configure the LCD module for the following using the LCDCON register:
   - Multiplex and Bias mode, bits LMUX<1:0>
   - Timing source, bits CS<1:0>
   - Sleep mode, bit SLPEN
4. Write initial values to pixel data registers, LCDDATA0 through LCDDATA21.
5. Clear LCD Interrupt Flag, LCDIF bit of the PIR2 register and if desired, enable the interrupt by setting bit LCDIE of the PIE2 register.
6. Configure bias voltages by setting the LCDRL, LCDREF and the associated ANSELx registers as needed.
7. Enable the LCD module by setting bit LCDEN of the LCDCON register.

19.13 Disabling the LCD Module

To disable the LCD module, write all '0's to the LCDCON register.

19.14 LCD Current Consumption

When using the LCD module the current consumption consists of the following three factors:

- Oscillator Selection
- LCD Bias Source
- Capacitance of the LCD segments

The current consumption of just the LCD module can be considered negligible compared to these other factors.

19.14.1 OSCILLATOR SELECTION

The current consumed by the clock source selected must be considered when using the LCD module. See **Section 22.0 "Electrical Specifications"** for oscillator current consumption information.

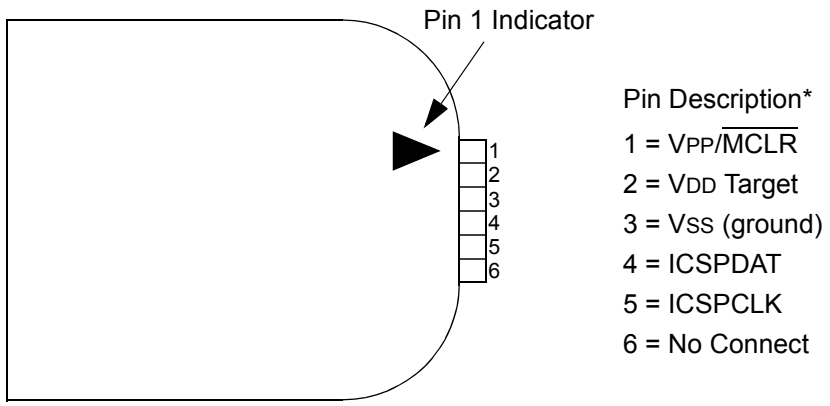
19.14.2 LCD BIAS SOURCE

The LCD bias source, internal or external, can contribute significantly to the current consumption. Use the highest possible resistor values while maintaining contrast to minimize current.

19.14.3 CAPACITANCE OF THE LCD SEGMENTS

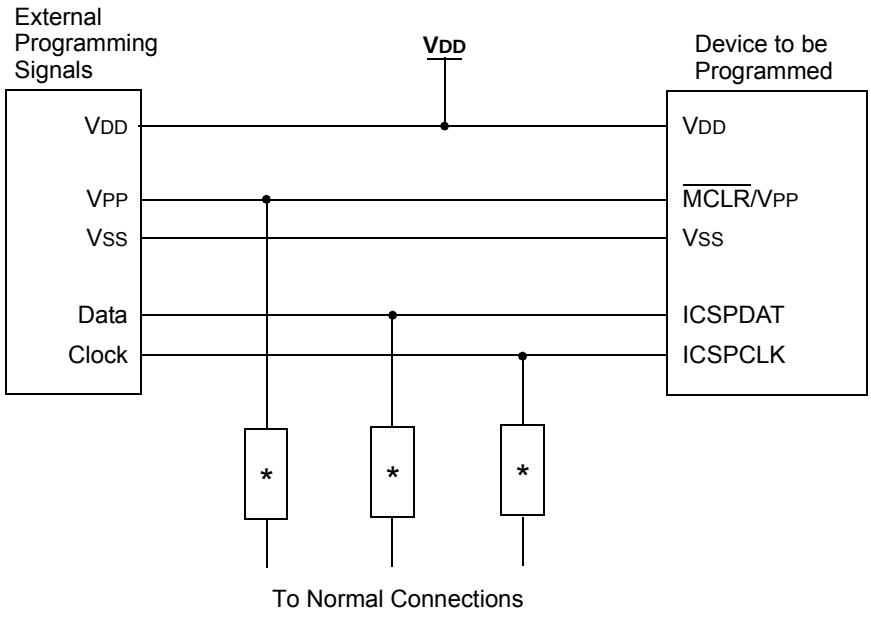
The LCD segments which can be modeled as capacitors which must be both charged and discharged every frame. The size of the LCD segment and its technology determines the segment's capacitance.

FIGURE 20-2: PICkit™ PROGRAMMER STYLE CONNECTOR INTERFACE



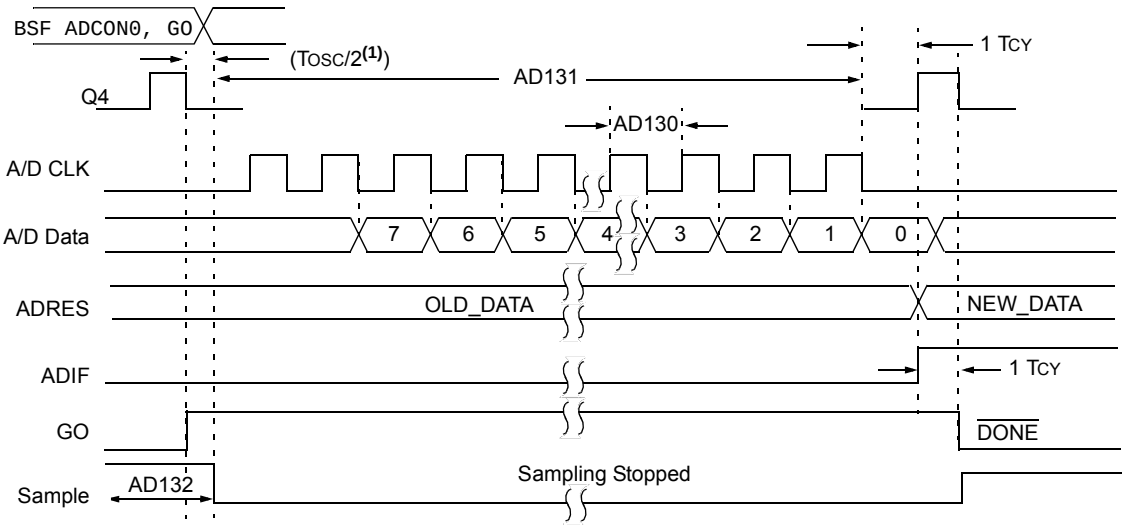
* The 6-pin header (0.100" spacing) accepts 0.025" square pins.

FIGURE 20-3: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



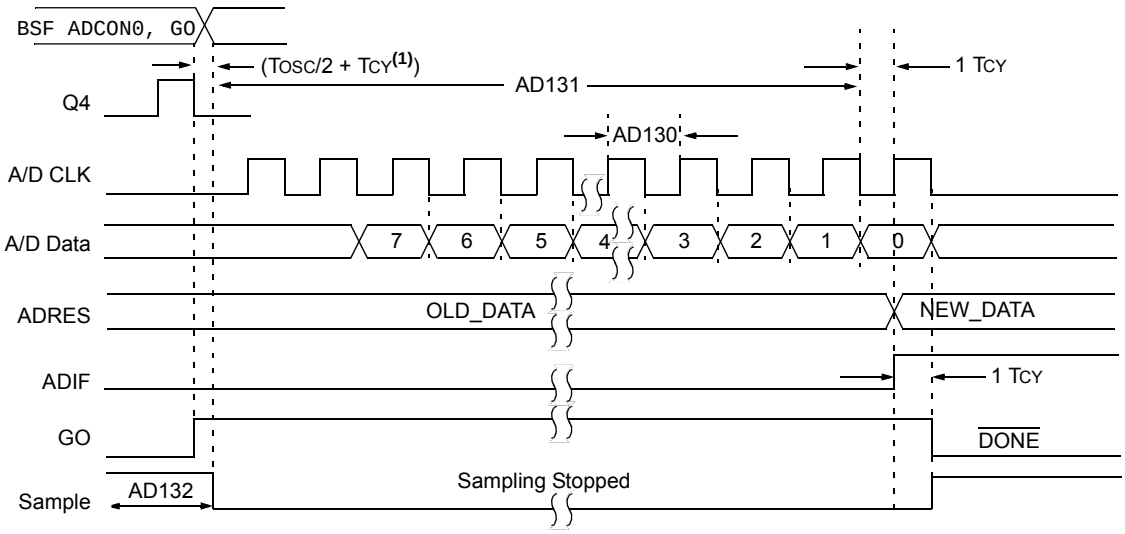
* Isolation devices (as required).

FIGURE 22-10: PIC16LF1904/6/7 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 22-11: PIC16LF1904/6/7 A/D CONVERSION TIMING (SLEEP MODE)

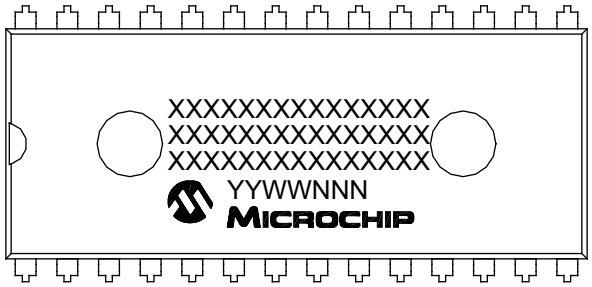


Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

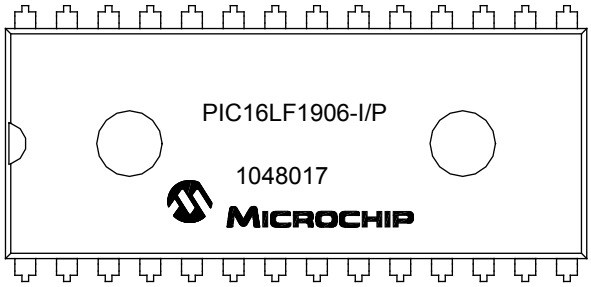
25.0 PACKAGING INFORMATION

25.1 Package Marking Information

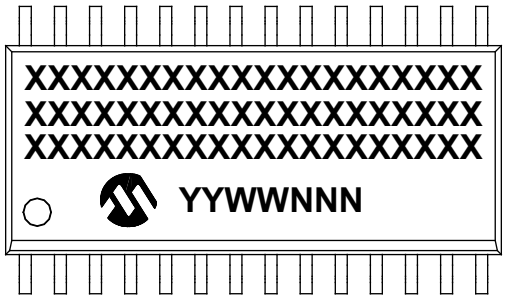
28-Lead PDIP (600 mil)



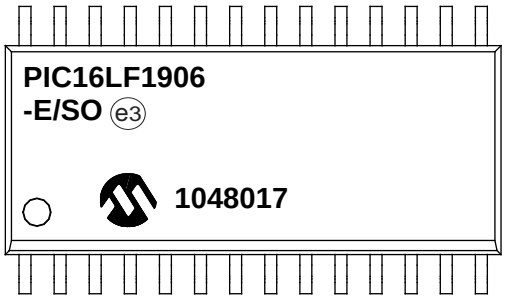
Example



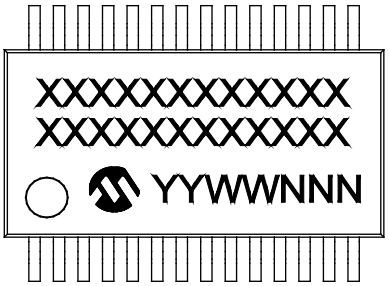
28-Lead SOIC (7.50 mm)



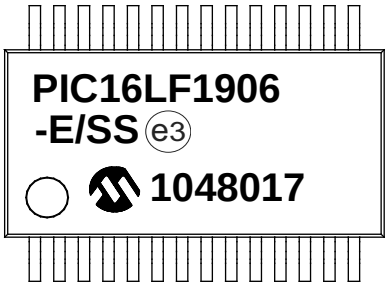
Example



28-Lead SSOP (5.30 mm)



Example

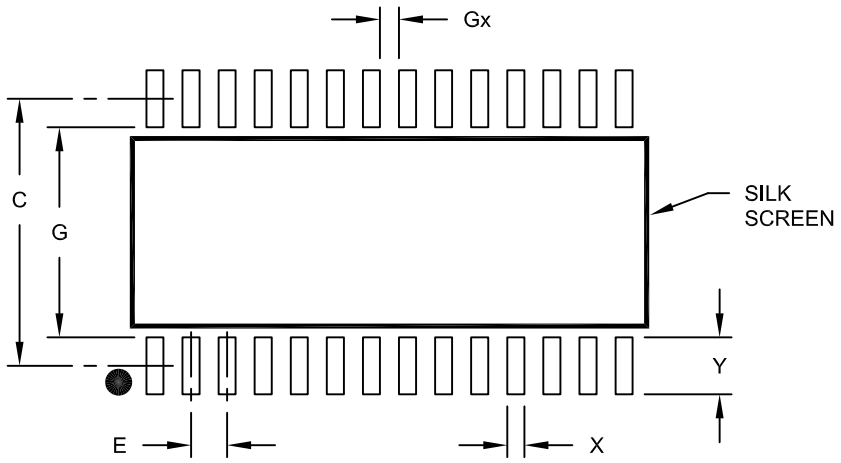


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
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